



SF206C Low Dk/Df聚酰亚胺薄膜覆盖膜

SF206C Low Dk/Df polyimide film based coverlay

特点

- 低介电常数, 低传输损耗
- 优秀的耐热性、耐化学性和电性能
- 不含卤素, 阻燃性达到 UL94 V-0 级
- 加工性好, 适于快速压合和传统压合
- 满足RoHS指令要求, 不含铅、汞、镉、六价铬、多溴联苯、多溴联苯醚等。

FEATURES

- Low dielectric constant, low dissipation loss.
- Excellent thermal resistance ,chemical resistance and electrical property
- Halogen-free, flammability UL94 VTM-0
- Good processability, suitable for both fast and traditional lamination style
- Compatible with EU RoHS directive, free of Pb Hg, Cd, Cr6+,PBB,PBDE, etc..

应用领域

高频印制板和刚挠性印制板

APPLICATIONS

Be used in high frequency FPC and rigid-flex PCB

性能表 GENERAL PROPERTIES

性能项目 Test Item		试验处理条件 Treatment Condition	单位 Unit	性能数据 Property Data	
				IPC 标准值* Standard	典型值 Typical Value
					SF206C 0515
热应力 Thermal Stress		288℃,20s	-	-	无分层、无起泡 No delamination
剥离强度 Peel Strength (90°)		A	N/mm	≥ 0.7	0.92
		288℃,5s		≥ 0.7	0.92
吸湿性 Moisture Absorption		E-1/105+D-24/23	%	≤ 4.0	0.53
尺寸稳定性 Dimensional Stability	MD	撕纸后 After peeling off the paper	%	± 0.2	± 0.15
	TD				± 0.15
介电常数 (10GHz) Dielectric Constant(10GHz)		C-24/23/50	-	≤ 4.0	2.76
介质损耗角正切 (10GHz) Dissipation Factor (10GHz)		C-24/23/50	-	≤ 0.04	0.0036
耐化学性 (剥离强度保持率) Chemical Resistance		暴露化学品后 After Chemical Exposure	%	≥ 80	>85

注释 Explanations: C = Humidity conditioning;

E = 恒温处理条件 Temperature conditioning.

1.与铜箔光面压合再固化后测试。Testing after laminating with shining side of copper foil in suitable condition.

* Certified to IPC-4203/21 Polyimide dielectric with polyimide adhesive



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产品规格代码描述 Product Code Description

SF206C 05 15

胶粘剂厚度 Adhesive Thickness: 15- 15 μ m; 25 - 25 μ m

PI 膜厚度 PI film Thickness: 05 – 12.5 μ m

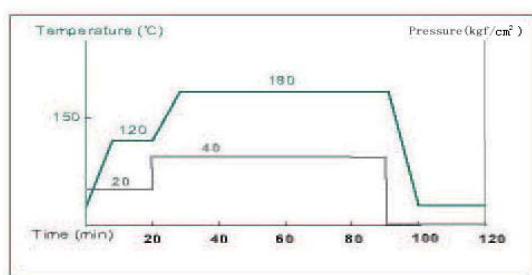
生益覆盖膜产品编号 Shengyi Coverlay Designation

常规产品表 SPECIFICATIONS OF STANDARD PRODUCTS

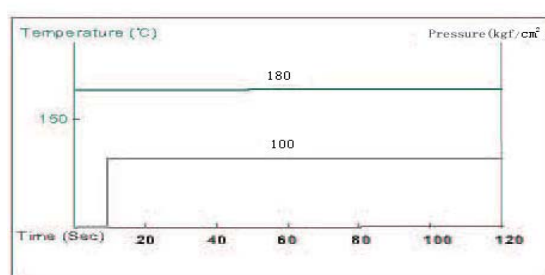
产品规格 Specifications	PI 膜厚度 (μ m) PI film Thickness (μ m)	胶粘剂厚度 (μ m) Adhesive Thickness (μ m)	应用领域 Applications
SF206C 0515	12.5	15	高频印制板和刚挠性 印制板 high frequency FPC and rigid-flex PCB
SF206C 0520	12.5	20	
SF206C 0525	12.5	25	
SF206C 1025	25	25	
SF206C 1030	25	30	

压板推荐 PRESS PROPOSE

HOT PRESSING CYCLE



FAST PRESSING CYCLE



传压参数根据不同设备及产品规格需作相应调整；采用快压方式，后固化条件是180℃、90-120分钟。

The parameters of hot Pressure need to be adjusted according to different equipment and product specifications. After fast press, the curing condition is 180 °C for 90-120min.

包装 PURCHASING INFORMATION

产品宽度250+2/-0mm或500+2/-0mm，每卷100+2/-0米或200+2/-0米；其它规格、尺寸可根据客户要求而定。SF206C is supplied in rolls and standard width of 250+2/-0mm or 500+2/-0mm. Roll length is 100+2/-0m or 200+2/-0m. Other sizes could be available upon request.

储存条件 STORAGE CONDITION

贮存在干燥的室内；以原始包装贮存在4-10℃的冷藏室里，贮存期为三个月。

Stored in the room of dryness . Three months when stored in the original packaging at 4-10 °C .